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(12) **United States Design Patent** (10) **Patent No.: US D802,472 S**
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(54) **ELECTROSTATIC CHUCK FOR SEMICONDUCTOR MANUFACTURING EQUIPMENT**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D11/182**
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USPC D13/182; D15/140
CPC H01L 21/67098; H01L 21/67109; H01L 21/683; H01L 21/6831; H01L 21/6833; H01L 21/6835; H01L 21/68; H01L 21/67; B23Q 3/15; B23Q 3/154; B23Q 3/1543; B23Q 3/1546; B23B 31/28; G03F 7/70708; G03F 7/707; H02N 13/00; H02N 15/00
See application file for complete search history.

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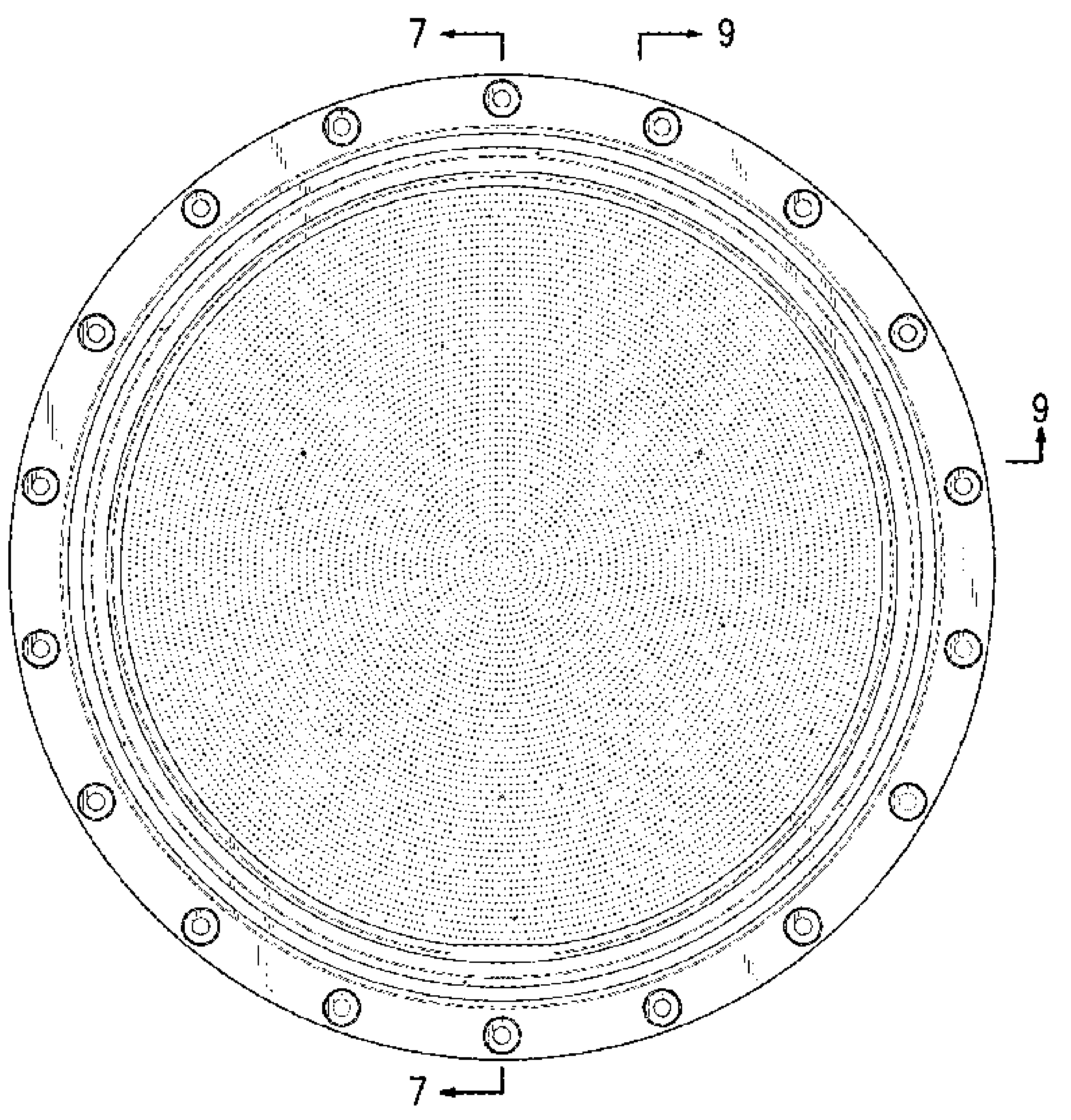
(57) **CLAIM**

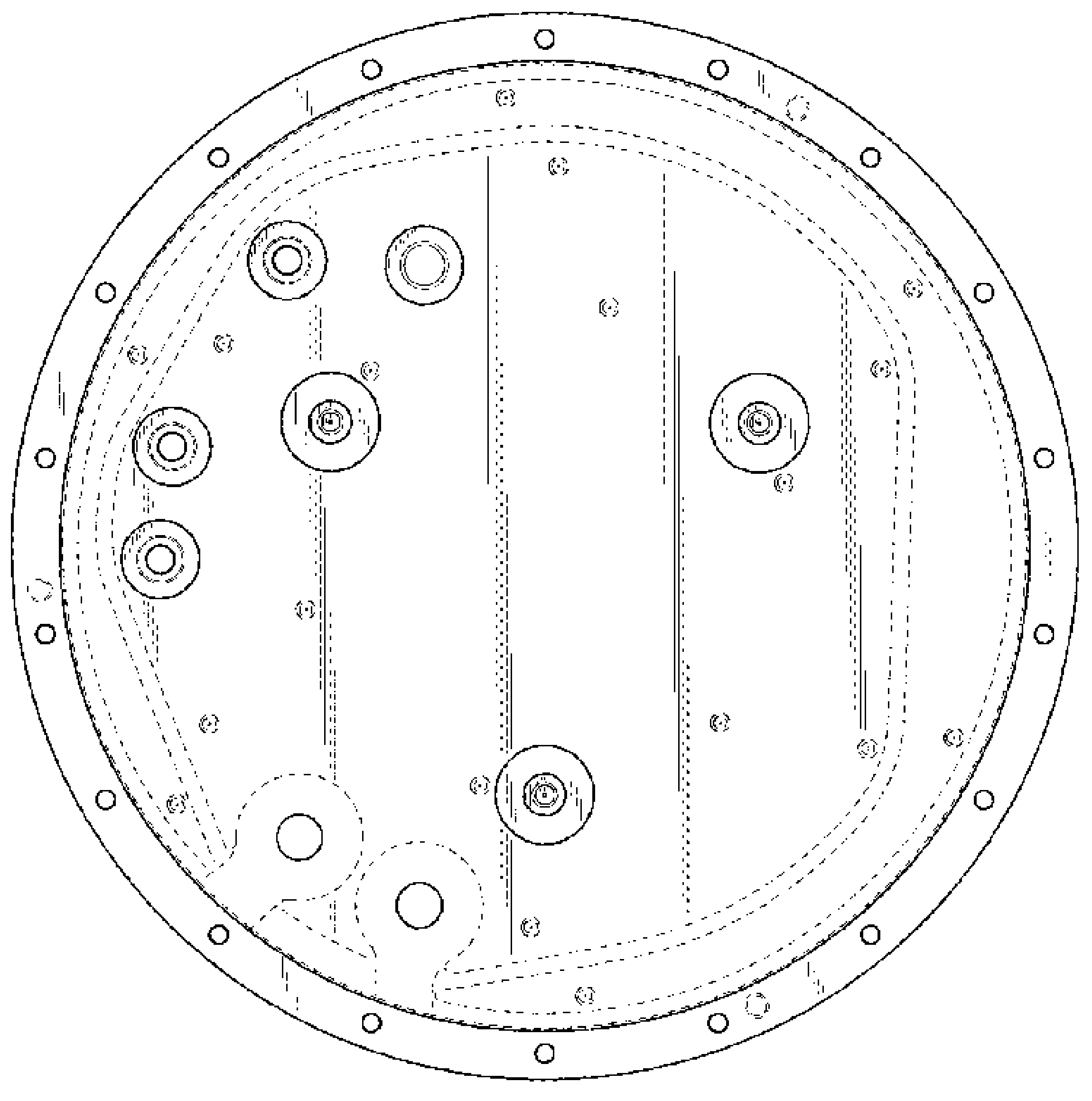
The ornamental design for an electrostatic chuck for semiconductor manufacturing equipment, as shown and described.

DESCRIPTION

FIG. **1** is a front view of an electrostatic chuck for semiconductor manufacturing equipment, showing our new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is a cross sectional view taken along the lines of **7-7** of FIG. **1**;
FIG. **8** is an enlarged view of a portion taken along lines of **8-8** of FIG. **7**; and,
FIG. **9** is an enlarged view of a portion taken along lines of **9-9** of FIG. **1**.
The features shown in broken lines depict environmental subject matter only and form no part of the claimed design.

1 Claim, 9 Drawing Sheets





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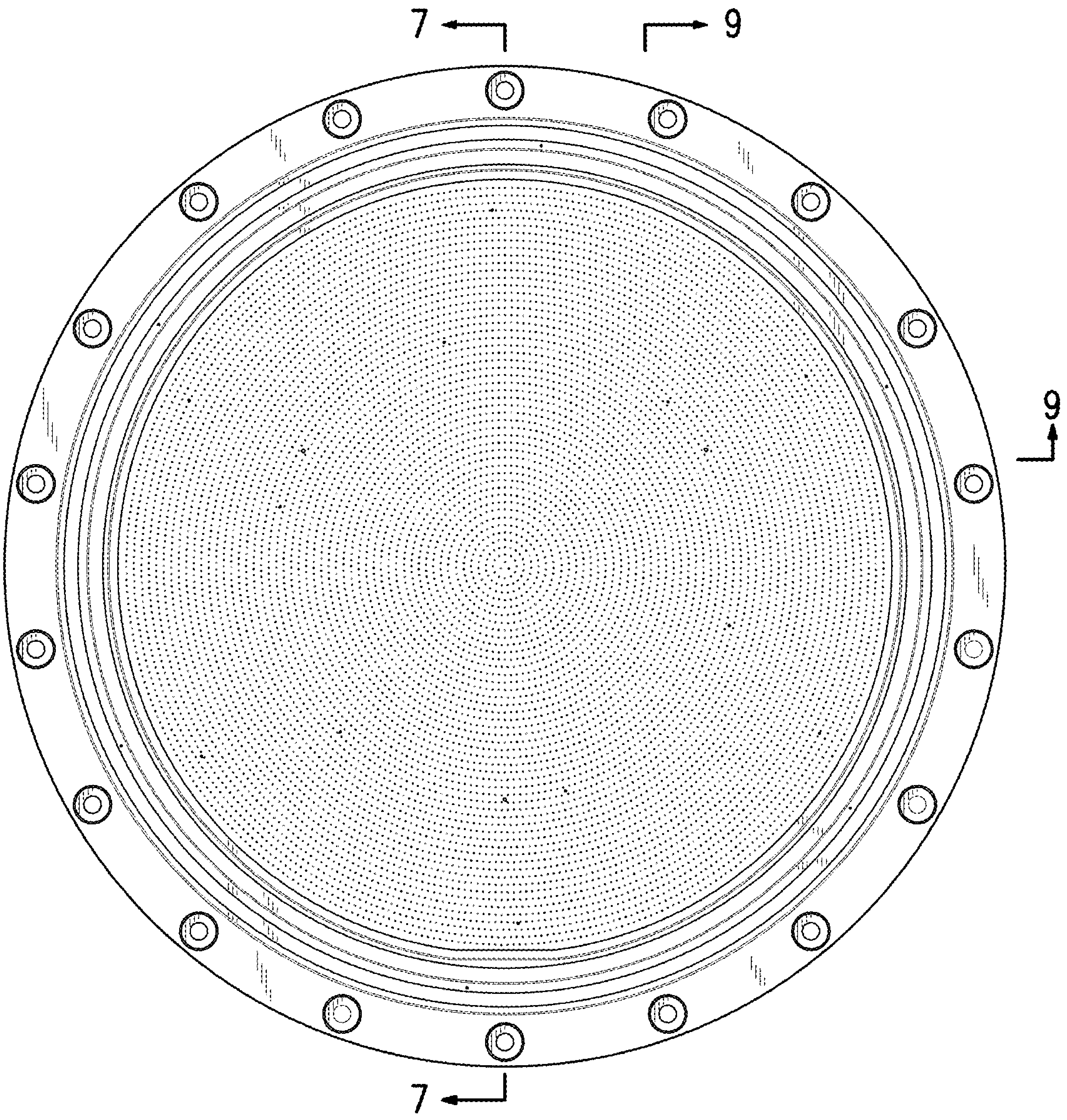

FIG. 1

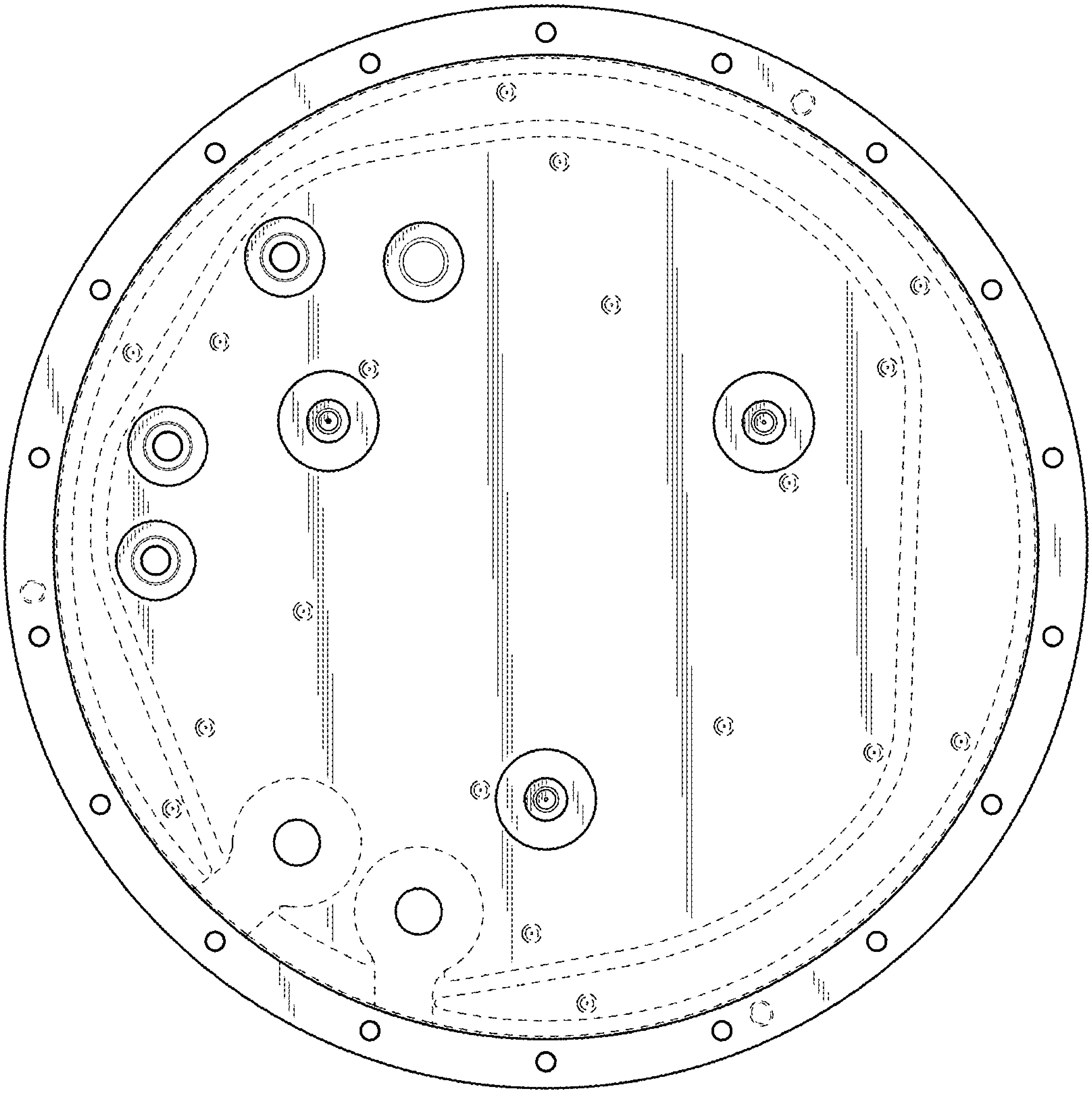

FIG. 2

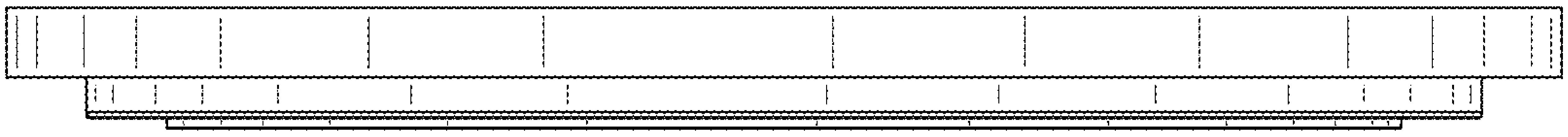

FIG. 3

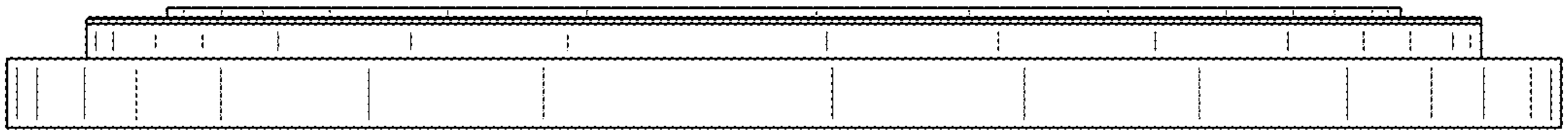

FIG. 4

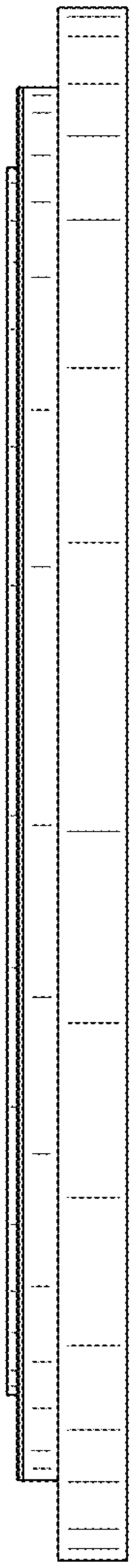

FIG. 5

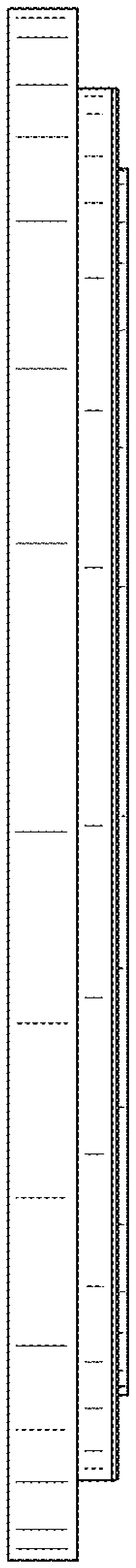

FIG. 6

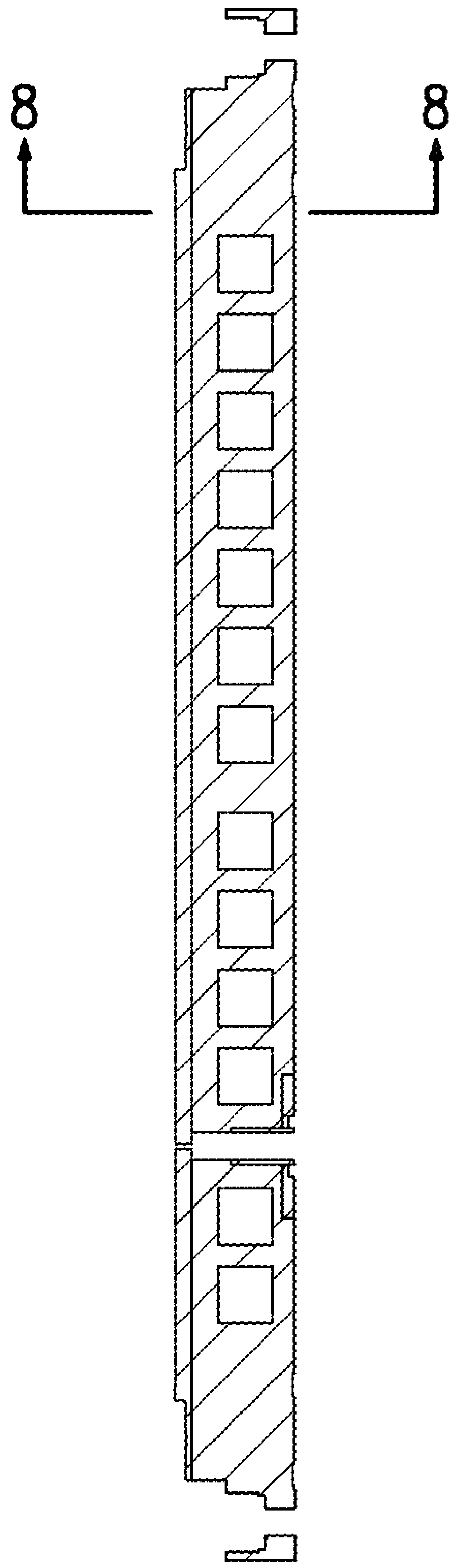

FIG. 7

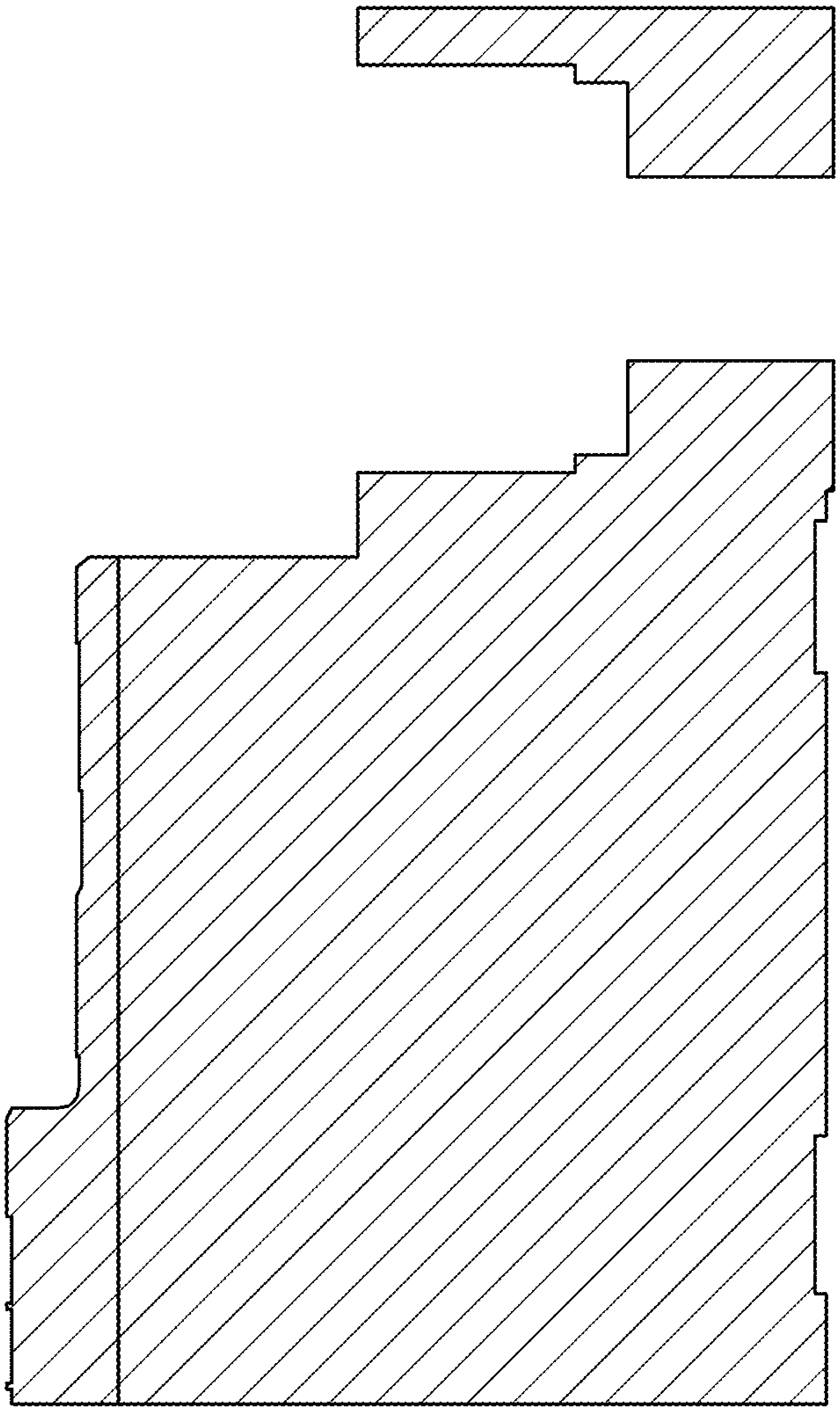

FIG. 8

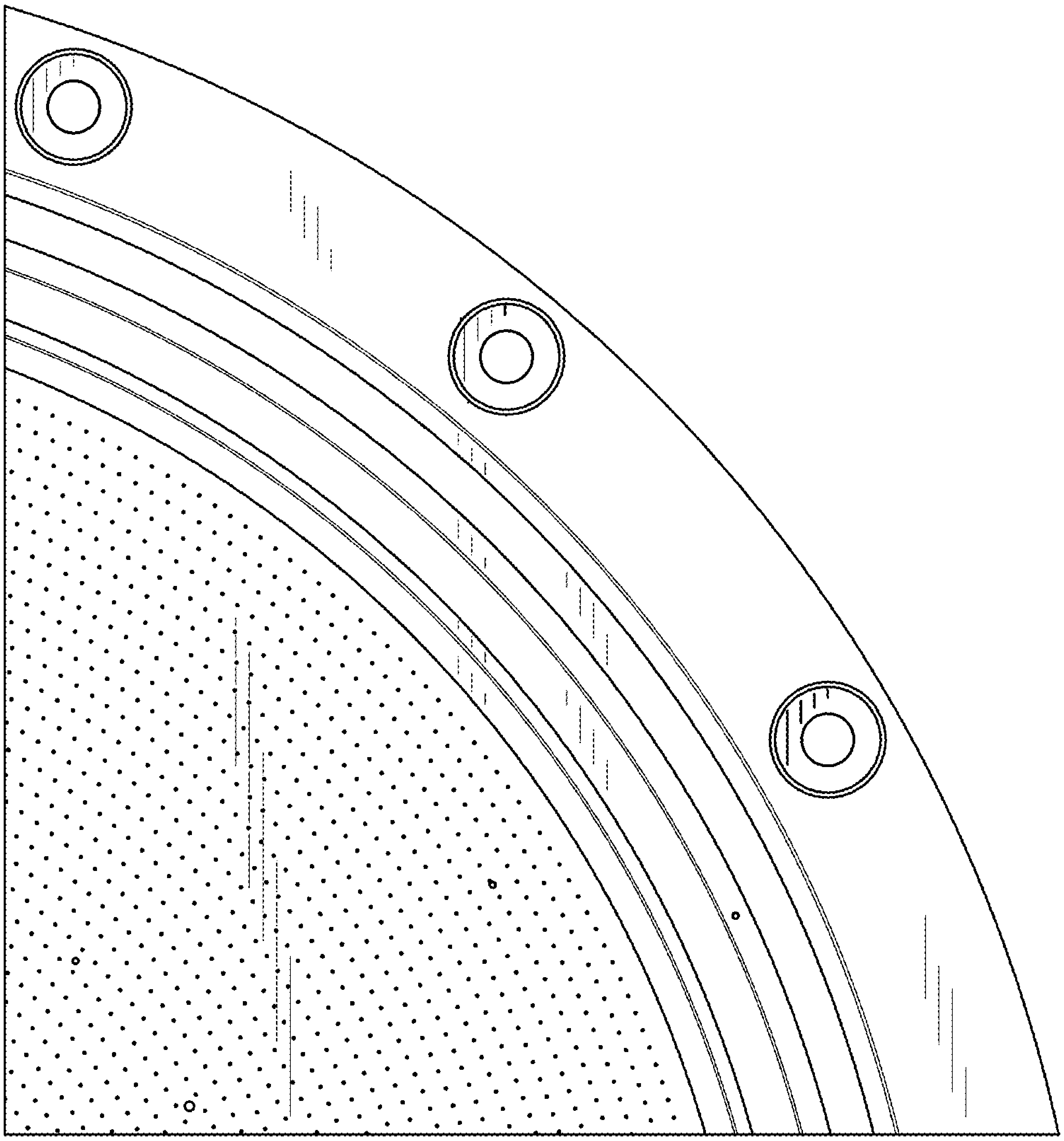

FIG. 9